



Surface Mount Surge Suppressors Bridge

FEATURES

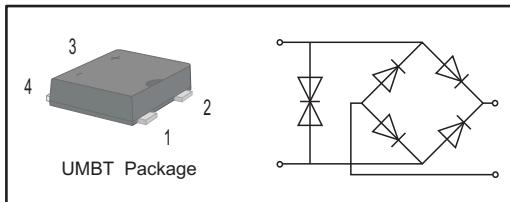
- Green Molding Compound (No Halogen and Antimony)
- Lower clamping voltage
- Glass Passivated Chip Junction
- High Surge Current Capability
- Designed for Surface Mount Application

MECHANICAL DATA

- Case: UMBT
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 60mg / 0.0021oz

PINNING

| PIN | DESCRIPTION |
|-----|--------------------|
| 1 | Input Pin (~) |
| 2 | Input Pin (~) |
| 3 | Output Anode (+) |
| 4 | Output Cathode (-) |



Maximum Ratings and Thermal Characteristics(TA = 25°C unless otherwise specified)

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

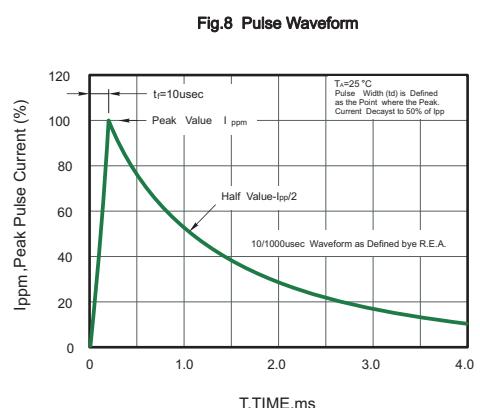
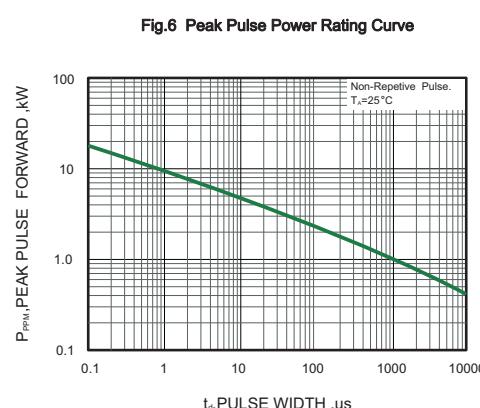
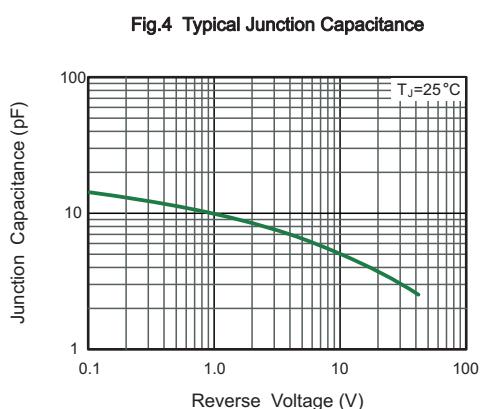
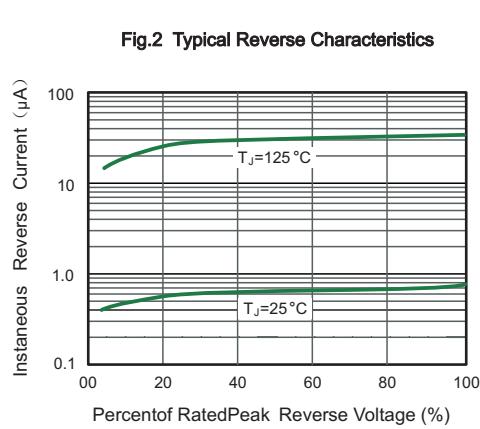
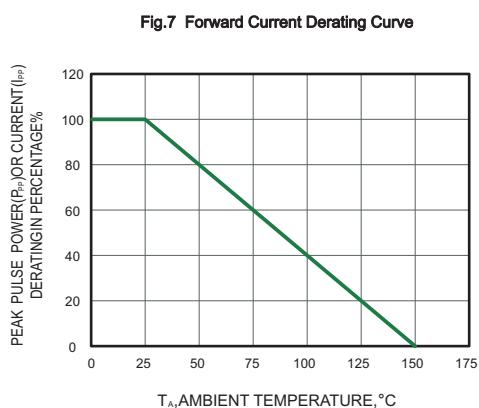
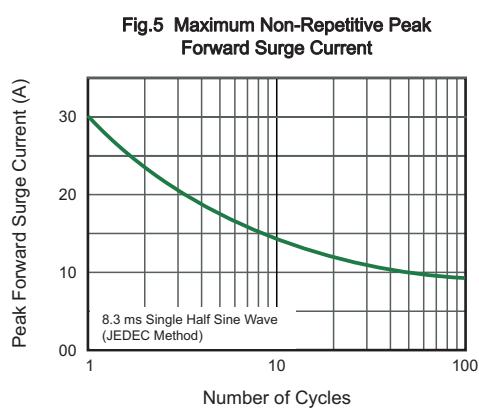
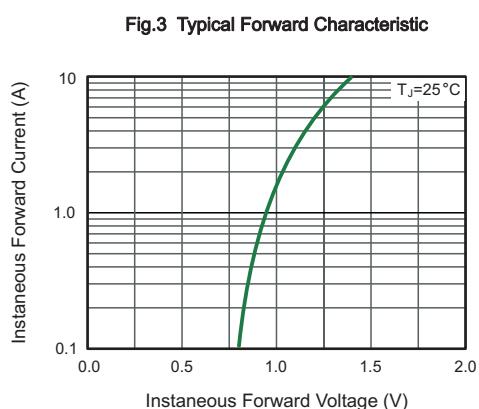
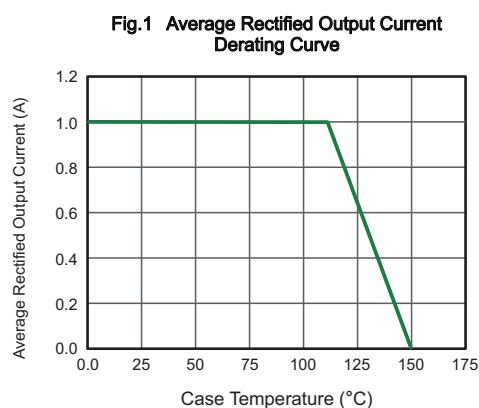
| Parameter of Bridge Rectifier | Symbols | TB110B | TB120B | TB240B | Units |
|--|--|--------|----------------|--------|-------|
| Average Rectified Output Current | I _o | | 1.0 | | A |
| Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method) | I _{FSM} | | 30 | | A |
| Maximum Forward Voltage at 1.0A | V _F | | 1.1 | | V |
| Maximum DC Reverse Current @T _A =25 °C at Rated DC Blocking Voltage (@VR=1000V) @T _A =125 °C | I _R | | 5 40 | | μA |
| Typical Junction Capacitance (f=1MHz,4V DC) | C _j | | 7 | | pF |
| Typical Thermal Resistance (Note1) | R _{θJA} R _{θJC} R _{θJL} | | 45 15 25 | | °C/W |
| Operating and Storage Temperature Range | T _j , T _{stg} | | -55 ~ +150 | | °C |

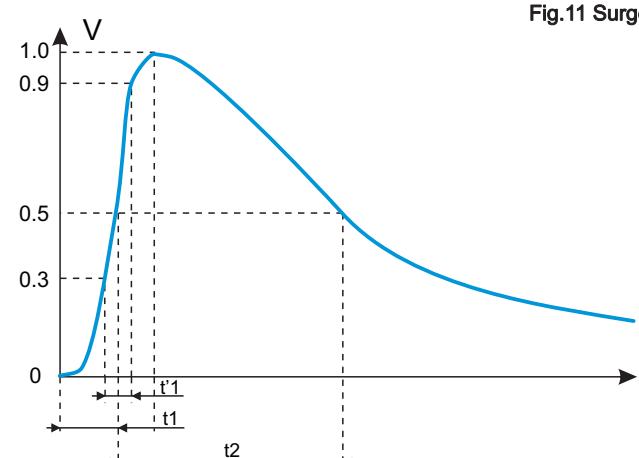
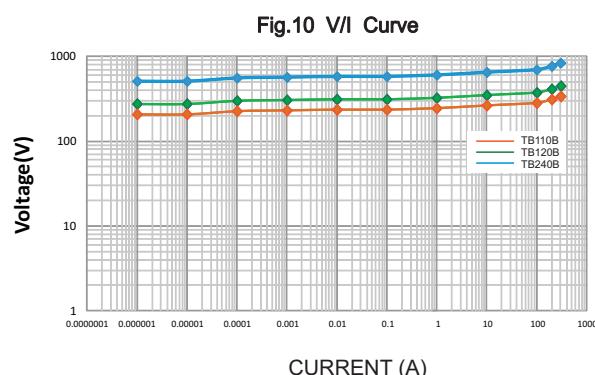
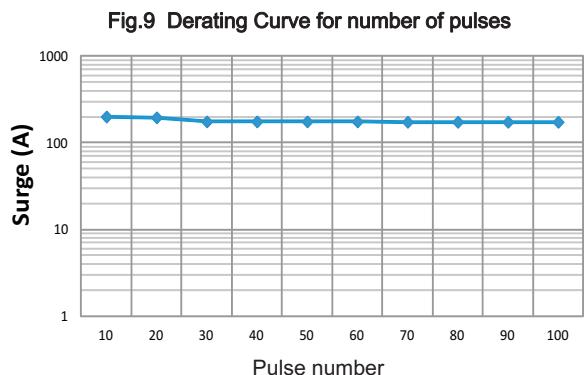
Note: 1. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

| Parameter of TVS | Symbol | TB110B | TB120B | TB240B | Unit |
|--|-----------------------------------|---------|------------|---------|------|
| Maximum allowable continuous AC voltage at 50-60Hz | V _{RMS} | 125 | 155 | 310 | V |
| Breakdown voltage | V _{BR} | 190~210 | 237~263 | 492~543 | V |
| Maximum allowable continuous DC voltage | V _{DC} | 170 | 220 | 440 | V |
| Maximum allowable clamping voltage | V _C | 300 | 350 | 700 | V |
| Maximum peak current | I _{peak} | | 200 | | A |
| Operating and Storage Temperature Range | T _j , T _{stg} | | -55 ~ +150 | | °C |

NOTES:

- 1.The breakdown voltage was measured at 1mA
2. The clamping voltage was measured at 8/20 μs standard current
3. The peak pulse current was tested at 8/20 μs waveform

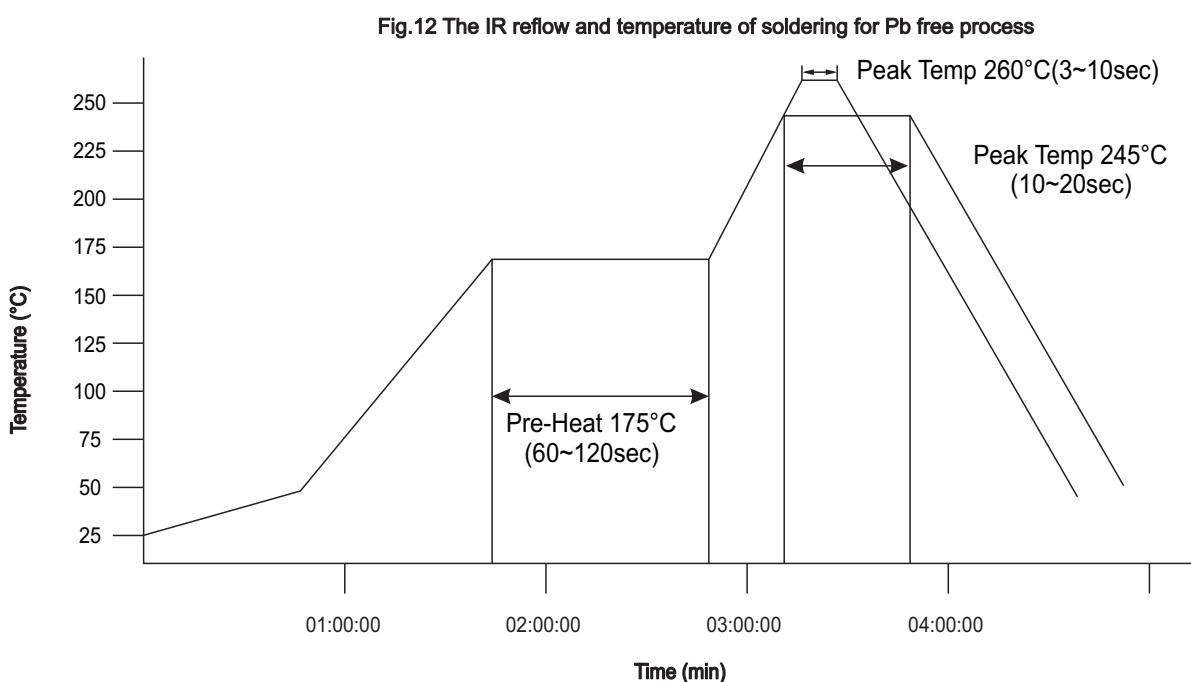




IEC61000-4-5 Standards

| SEVERITY LEVEL | T1(=1.67t'1) | T2 |
|----------------|--------------|--------|
| 1 | 10us | 1000us |
| 2 | 8us | 20us |

8/20us waveform current



IR reflow Pb free process suggestion profile :

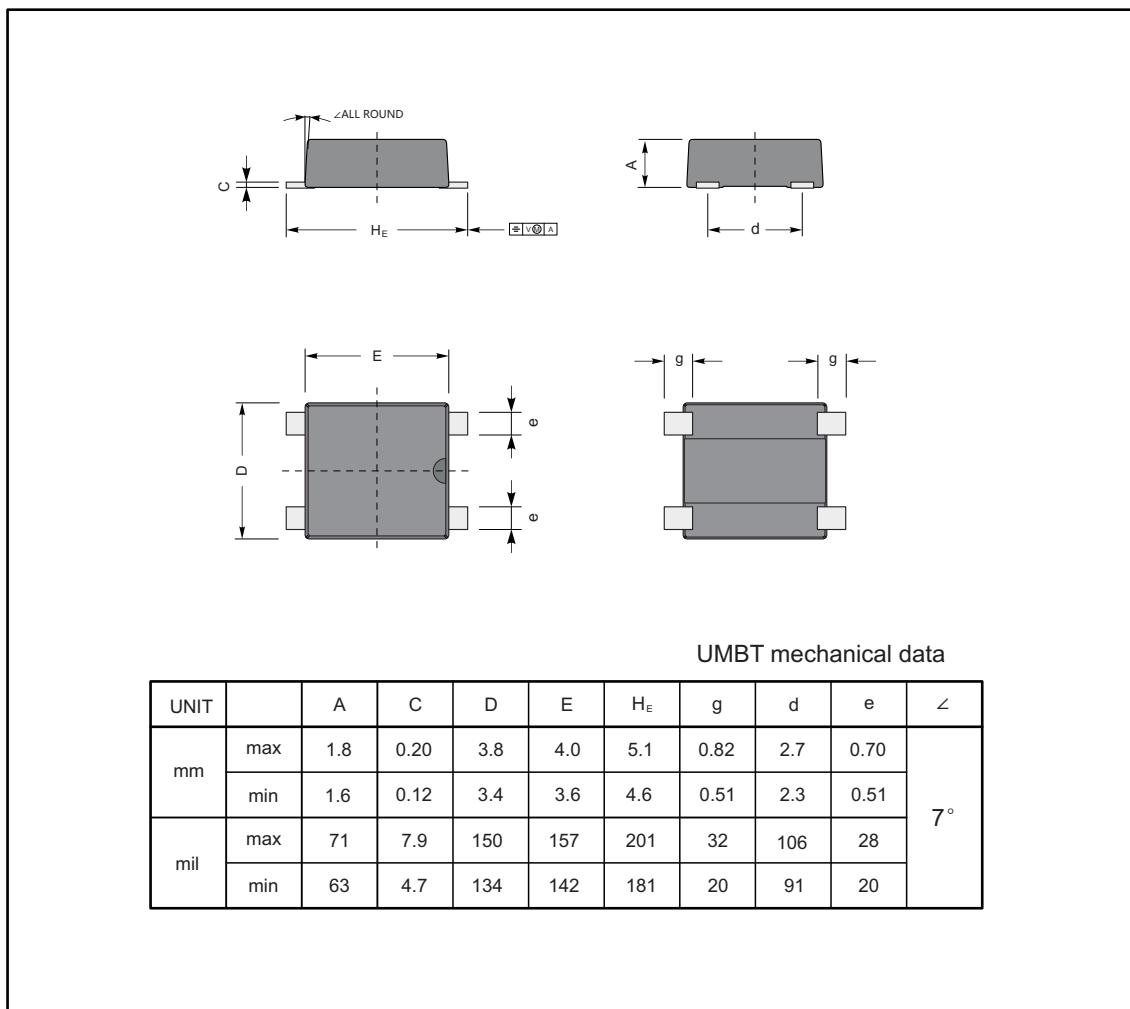
- (1) Ramp-up rate (217°C to peak) +3°C/second max.
- (2) Temp. maintain at 175±25 180seconds max.
- (3) Temp. maintain above 217°C 60~150 seconds
- (4) The peak temperature must be at least 260°C, the time above the 255°C must be within 20s



PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

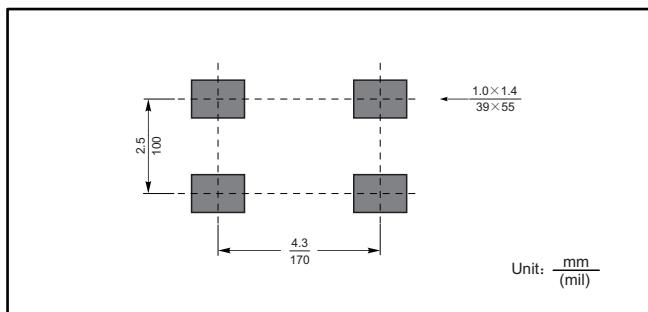
UMBТ



UMBТ mechanical data

| UNIT | | A | C | D | E | H _E | g | d | e | < |
|------|-----|-----|------|-----|-----|----------------|------|-----|------|----|
| mm | max | 1.8 | 0.20 | 3.8 | 4.0 | 5.1 | 0.82 | 2.7 | 0.70 | 7° |
| | min | 1.6 | 0.12 | 3.4 | 3.6 | 4.6 | 0.51 | 2.3 | 0.51 | |
| mil | max | 71 | 7.9 | 150 | 157 | 201 | 32 | 106 | 28 | 7° |
| | min | 63 | 4.7 | 134 | 142 | 181 | 20 | 91 | 20 | |

The recommended mounting pad size



Marking

| Type number | Marking code |
|-------------|--------------|
| TB110B | T110B |
| TB120B | T120B |
| TB240B | T240B |



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